DL PACKAGE

SCAS209C - APRIL 1992 - REVISED APRIL 1998

- **Member of the Texas Instruments** Widebus™ Family
- Load Clock and Unload Clock Can Be **Asynchronous or Coincident**
- 64 Words by 18 Bits
- Low-Power Advanced CMOS Technology
- Full, Empty, and Half-Full Flags
- Programmable Almost-Full/Almost-Empty
- Fast Access Times of 15 ns With a 50-pF Load and All Data Outputs Switching Simultaneously
- Data Rates up to 50 MHz
- 3-State Outputs
- Pin-to-Pin Compatible With SN74ACT7804 and SN74ACT7806
- Packaged in Shrink Small-Outline 300-mil Package Using 25-mil Center-to-Center Spacing

description

A FIFO memory is a storage device that allows data to be written into and read from its array at independent data rates. The SN74ACT7814 is a 64-word by 18-bit FIFO for high speed and fast access times. It processes data at rates up to 50 MHz and access times of 15 ns in a bit-parallel format.

Data is written into memory on a low-to-high transition at the load clock (LDCK) input and is read out on a low-to-high transition at the unload clock (UNCK) input. The memory is full when the number of words clocked in exceeds the number of words clocked out by 64. When the memory is full, LDCK signals have no effect on the data residing in memory. When the memory is empty, UNCK signals have no effect.

(TOP VIEW) RESET 56 ∏ OE D17 🛮 2 55 Q17 D16 **∏**3 54 ¶ Q16 53 Q15 D15 ∏4 D14 🛮 5 52 GND 51 Q14 D13 **[**]6 D12 Π_7 50 V_{CC} D11 [] 8 49 **∏** Q13 D10 **1**9 48 Q12 V_{CC} [] 10 47 Q11 D9 [] 11 46 Q10 45 🛮 Q9 D8 🛮 12 GND 1 13 44 II GND D7 ∏ 43 **∏** Q8 14 42 Q7 D6 🛮 15 41 🛮 Q6 D5 **∏**16 D4 Π 40 ∏ Q5 17 D3 [18 39 V_{CC} D2 ¶ 19 38 **∏** Q4 37 Q3 D1 [20 D0 []21 36∏ Q2 HF **∏**22 35 ∏ GND PEN 34 🛮 Q1 23 AF/AE [24 33 Q0 LDCK II 25 32 II UNCK NC [] 26 31 NC NC 1 27 30 NC FULL 28 29 EMPTY

Status of the FIFO memory is monitored by the full (FULL), empty (EMPTY), half-full (HF), and almost-full/almost-empty (AF/AE) flags. The FULL output is low when the memory is full and high when the memory is not full. The EMPTY output is low when the memory is empty and high when it is not empty. The HF output is high when the FIFO contains 32 or more words and is low when it contains 31 or fewer words. The AF/AE status flag is a programmable flag. The first one or two low-to-high transitions of LDCK after reset are used to program the almost-empty offset value (X) and the almost-full offset value (Y) if program enable (PEN) is low. The AF/AE flag is high when the FIFO contains X or fewer words or (64 - Y) or more words. The AF/AE flag is low when the FIFO contains between (X + 1) and (63 - Y) words.



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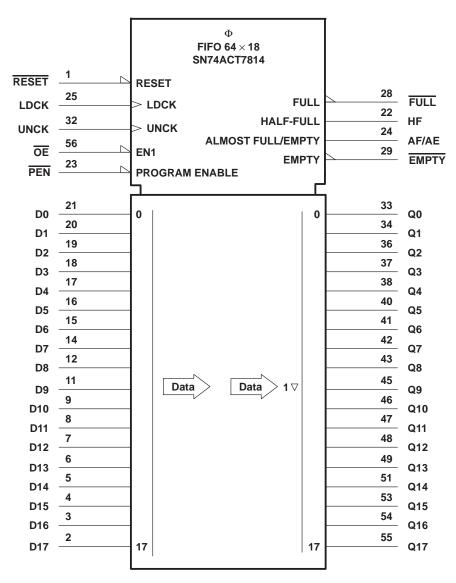
STRUMENTS

description (continued)

A low level on the reset (RESET) input resets the internal stack pointers and sets FULL high, HF low, and EMPTY low. The Q outputs are not reset to any specific logic level. The FIFO must be reset upon power up. The first word loaded into empty memory causes EMPTY to go high and the data to appear on the Q outputs. It is important to note that the first word does not have to be unloaded. The data outputs are noninverting with respect to the data inputs and are in the high-impedance state when the output-enable (OE) input is high.

The SN74ACT7814 is characterized for operation from 0°C to 70°C.

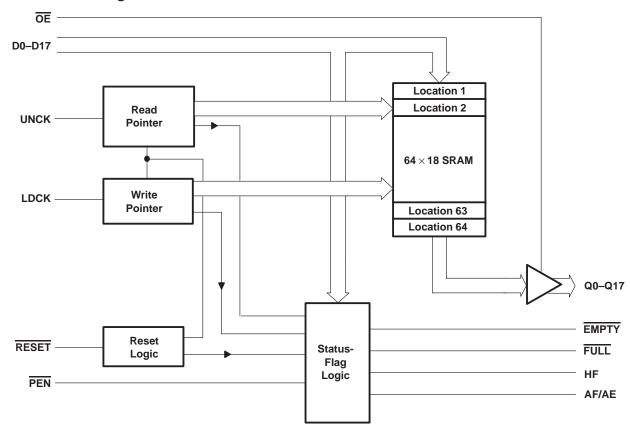
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



functional block diagram



Terminal Functions

TERMINAL			DECORPTION
NAME	NO.	I/O	DESCRIPTION
AF/AE	24	0	Almost-full/almost-empty flag. Depth-offset values can be programmed for AF/AE, or the default value of 8 can be used for both the almost-empty offset (X) and the almost-full offset (Y). AF/AE is high when memory contains X or fewer words or (64 – Y) or more words. AF/AE is high after reset.
D0-D17	2–9, 11–12, 14–21	ı	18-bit data input port
EMPTY	29	0	Empty flag. EMPTY is high when the FIFO memory is not empty; EMPTY is low when the FIFO memory is empty or upon assertion of RESET.
FULL	28	0	Full flag. FULL is high when the FIFO memory is not full or upon assertion of RESET; FULL is low when the FIFO memory is full.
HF	22	0	Half-full flag. HF is high when the FIFO memory contains 32 or more words. HF is low after reset.
LDCK	25	Ι	Load clock. Data is written to the FIFO on the rising edge of LDCK when FULL is high.
ŌĒ	56	- 1	Output enable. When OE is high, the data outputs are in the high-impedance state.
PEN	23	-	Program enable. After reset and before the first word is written to the FIFO, the binary value on D0–D4 is latched as an AF/AE offset value when PEN is low and WRTCLK is high.
Q0-Q17	33–34, 36–38, 40–43, 45–49, 51, 53–55	0	18-bit data output port
RESET	1	I	Reset. A low level on RESET resets the FIFO and drives FULL high and HF and EMPTY low.
UNCK	32	I	Unload clock. Data is read from the FIFO on the rising edge of UNCK when EMPTY is high.



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offset values for AF/AE

The AF/AE flag has two programmable limits: the almost-empty offset value (X) and the almost-full offset value (Y). They can be programmed after the FIFO is reset and before the first word is written to memory. The AF/AE flag is high when the FIFO contains X or fewer words or (64 - Y) or more words.

To program the offset values, \overline{PEN} can be brought low after reset only when LDCK is low. On the following low-to-high transition of LDCK, the binary value on D0–D4 is stored as the almost-empty offset value (X) and the almost-full offset value (Y). Holding \overline{PEN} low for another low-to-high transition of LDCK reprograms Y to the binary value on D0–D4 at the time of the second LDCK low-to-high transition. Writes to the FIFO memory are disabled while the offsets are programmed. A maximum value of 31 can be programmed for either X or Y (see Figure 1). To use the default values of X = Y = 8, \overline{PEN} must be held high.

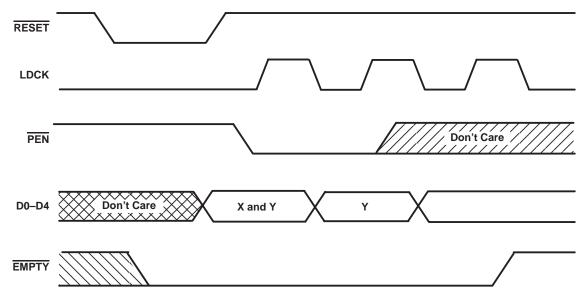


Figure 1. Programming X and Y Separately



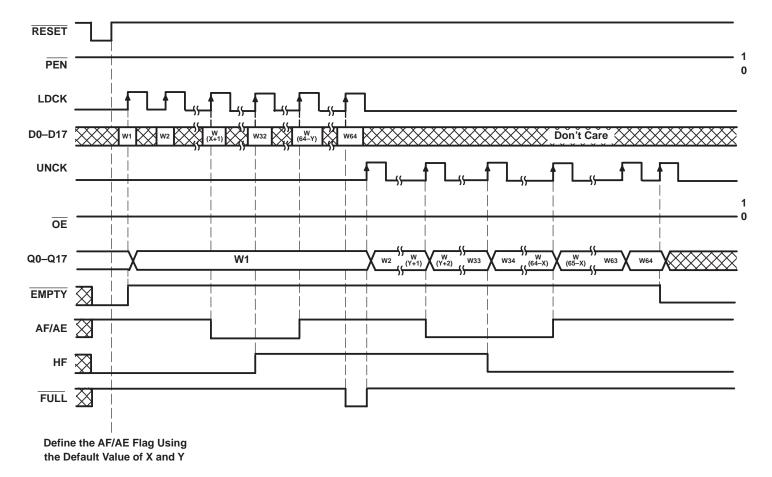


Figure 2. Write, Read, and Flag Timing Reference

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

recommended operating conditions

		,			'ACT7814-25		'ACT78	UNIT		
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT	
Vcc	Supply voltage		4.5	5.5	4.5	5.5	4.5	5.5	V	
VIH	High-level input voltage		2		2		2		V	
VIL	Low-level input voltage			0.8		0.8		0.8	V	
ІОН	High-level output current	Q outputs, flags		-8		-8		-8	mA	
1	Lour lovel output ourroat	Q outputs		16		16		16	A	
IOL	Low-level output current	Flags		8		8		8	mA	
TA	Operating free-air temperature		0	70	0	70	0	70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER TEST CONDITIONS				ONS	MIN	TYP‡	MAX	UNIT
Vон		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -8 \text{ mA}$		2.4			V
V/01	Flags	$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 8 \text{ mA}$				0.5	V
VOL	Q outputs	$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 16 \text{ mA}$				0.5	V
II		$V_{CC} = 5.5 \text{ V},$	$V_I = V_{CC}$ or 0				±5	μΑ
loz		$V_{CC} = 5.5 \text{ V},$	$V_O = V_{CC}$ or 0				±5	μΑ
Icc		$V_{I} = V_{CC} - 0.2 V$	or 0				400	μΑ
∆lcc§		V _C C = 5.5 V,	One input at 3.4 V,	Other inputs at V _{CC} or GND			1	mA
Ci		V _I = 0,	f = 1 MHz			4		pF
Со		$V_{O} = 0$,	f = 1 MHz			8		pF

 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_A = 25°C.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51.

[§] This is the supply current for each input that is at one of the specified TTL voltage levels rather 0 V or VCC.

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timing requirements over recommended operating conditions (see Figures 1 through 3)

			'ACT78	'ACT7814-20		14-25	'ACT7814-40		UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT	
fclock	Clock frequency			50		40		25	MHz	
		LDCK high or low	7		8		12			
١.	Pulse duration	UNCK high or low	7		8		12		ns	
l t _W	ruise duration	PEN low	7		8		12		115	
		RESET low	10		10	10				
		D0-D17 before LDCK↑	5		5		5			
t _{su}	Setup time	PEN before LDCK↑	5		5		5		ns	
		LDCK inactive before RESET high			6		6			
		D0-D17 after LDCK↑	0		0		0			
 	Hold time	LDCK inactive after RESET high			6		6		1	
t _h	HOIU IIIIIE	PEN low after LDCK↑	3		3		3		ns	
		PEN high after LDCK↓	0		0		0			

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 3)

DADAMETED	FROM	то	'A	CT7814-:	20	'ACT78	14-25	'ACT78	LINUT	
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNIT
f _{max}	LDCK or UNCK		50			40		25		MHz
	LDCK↑	Amy O	9		20	9	22	9	24	
^t pd	UNCK1	Any Q	6	11.5	15	6	18	6	20	ns
t _{pd} ‡	UNCK↑	Any Q		10.5						ns
^t PLH	LDCK↑	EMPTY	6		15	6	17	6	19	ns
	UNCK [↑]	=145=14	6		15	6	17	6	19	
t _{PHL}	RESET low	EMPTY	4		16	4	18	4	20	ns
	LDCK↑	FULL	6		15	6	17	6	19	
t	UNCK [↑]		6		15	6	17	6	19	ns
^t PLH	RESET low	FULL	4		18	4	20	4	22	
.	LDCK↑	AF/AE	7		18	7	20	7	22	ns
^t pd	UNCK↑	AF/AE	7		18	7	20	7	22	115
tour	RESET low	AF/AE	2		10	2	12	2	14	ns
^t PLH	LDCK↑	HF	5		18	5	20	5	22	115
+=	UNCK↑	HF	7		18	7	20	7	22	20
^t PHL	RESET low	ПГ	3		12	3	14	3	16	ns
t _{en}	ŌĒ	Any Q	2		9	2	10	2	11	ns
t _{dis}	ŌĒ	Any Q	2		10	2	11	2	12	ns

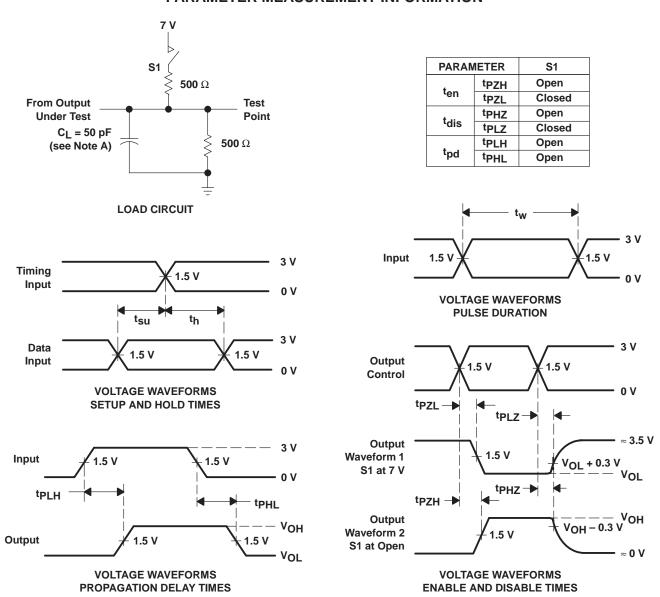
operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER			TEST CO	TYP	UNIT	
C _{pd}	Power dissipation capacitance per FIFO channel	Outputs enabled	$C_L = 50 \text{ pF},$	f = 5 MHz	53	pF



 $[\]uparrow$ All typical values are at V_{CC} = 5 V, T_A = 25°C. \uparrow This parameter is measured at C_L = 30 pF (see Figure 4).

PARAMETER MEASUREMENT INFORMATION

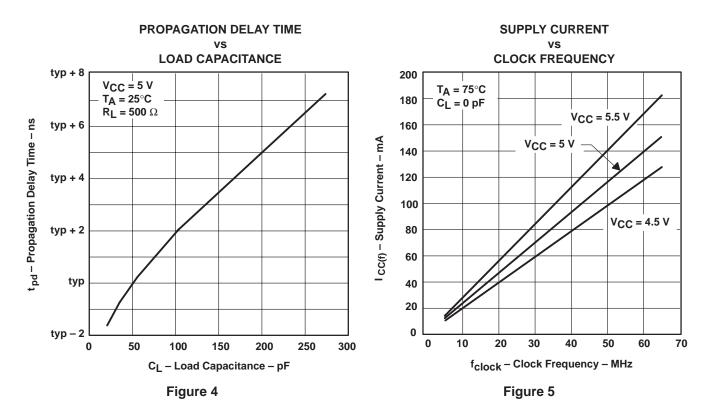


NOTE A: C_L includes probe and jig capacitance.

Figure 3. Load Circuit and Voltage Waveforms



TYPICAL CHARACTERISTICS



APPLICATION INFORMATION

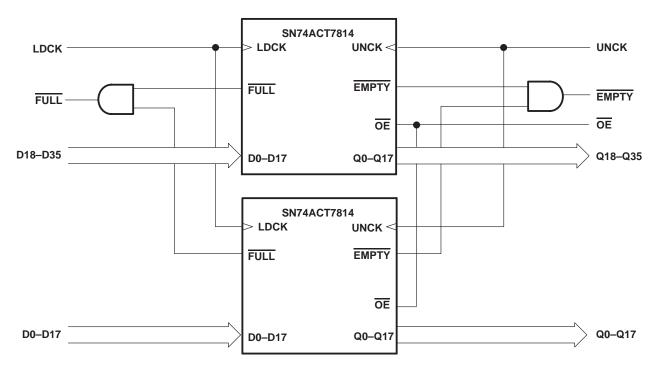


Figure 6. Word-Width Expansion: 64×36 Bits



www.ti.com 11-Nov-2025

PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
SN74ACT7814-20DL	Active	Production	SSOP (DL) 56	20 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	ACT7814-20
SN74ACT7814-20DL.A	Active	Production	SSOP (DL) 56	20 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	ACT7814-20
SN74ACT7814-40DL	Active	Production	SSOP (DL) 56	20 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	ACT7814-40
SN74ACT7814-40DL.A	Active	Production	SSOP (DL) 56	20 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	ACT7814-40

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

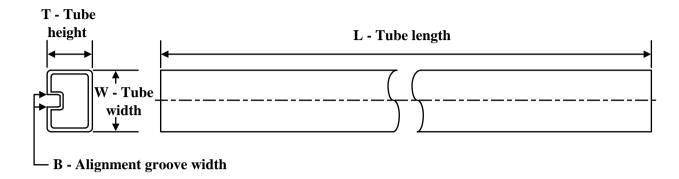
⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

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TUBE

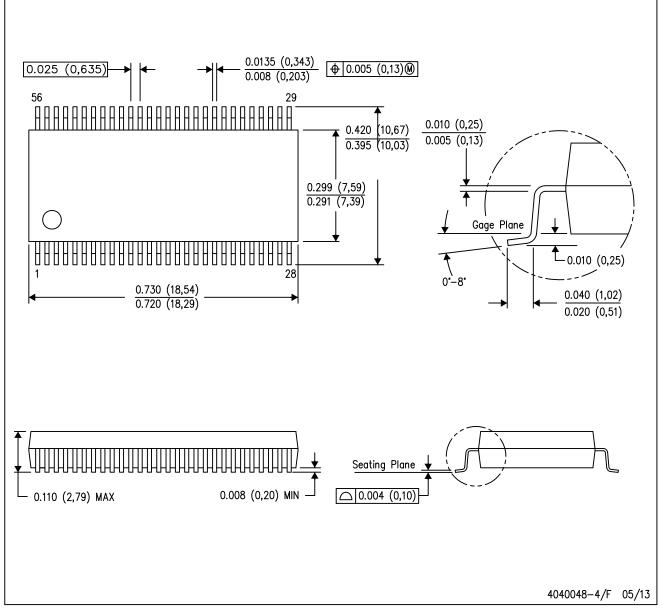


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ACT7814-20DL	DL	SSOP	56	20	473.7	14.24	5110	7.87
SN74ACT7814-20DL.A	DL	SSOP	56	20	473.7	14.24	5110	7.87
SN74ACT7814-40DL	DL	SSOP	56	20	473.7	14.24	5110	7.87
SN74ACT7814-40DL.A	DL	SSOP	56	20	473.7	14.24	5110	7.87

DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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